



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR QFN16 3 x 3 SOLDER PROCESS					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
Bond Integrity	160	80 000	200 °C + N2	0	0.00
HAST	561	56 100	130 °C, 85 % RH	0	0.00
Pressure Pot	656	62 976	121 °C, 15 PSIG	0	0.00
Solder DUNK	301	903	260 °C, 10 s	0	0.00
Temp. Cycle	658	617 000	-65 °C to +150 °C	0	0.00